	Material Comp © Copyright 2005. I international and Par	osition Dee PC, Bannockt	claration ourn, Illinois. A opyright conve	Il rights reserved untions.	under both level	documen parts, the	nt is a declaration e declaration en	n of the substanc compasses all lo	es within the wer level ma	e manufacture terials for wh	er listed it hich the m	em. Note: if anufacturer	the item is an as has engineering	sembly with lowe responsibility.
1752-21.1	1 IPC Web Site for Information on IPC-1752 Standard Form T				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				eous Materia	ials and Mfg Information			
Supplier	r Information													
Company name* Con				Company unique ID			Unique ID Authority				Response Date*			
onsemi											2025-07-03			
Contact N	lame		Title - Contact			Pł	Phone - Contact*				Email - Contact*			
Product-H	Env-Stewards		Product Enviro Compliance			Ν	NA				Product-Env-Stewards@onsemi.com			
uthorize	d Representative*		Title - Representative			Pł	Phone - Representative*				Email - Representative*			
Product-H	Env-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		n Number Mfr Item Name			E	Effective Date	Version	Version Manufacturing Site		V	Veight*	UOM	Unit Type
		NVH4L(NVH4L040N120SC1 SiC MOS TO247-4		7-4L 1200V 40mohm a	auto 2	2025-07-03	-07-03 CPA			6	378.37	mg	Each
Aanufa	cturing Proccess Informa	tion												
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 I		J-STD-020 MSL Ratii	ng	Peak Process Body Temperat		ure Max Time at Peak Temper		Temperati	ire Numb	er of Reflow Cyc	cles
Matte Tin (Sn) - annealed			U Alloy NA				0 C 30				seconds 3			
omments	6													
o r more i	information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless	otherwise noted).							
Homogeneous Material Weight Unit of Measure		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.29	mg	Supplier	Silicon Carbide	409-21-2		5.29	mg
Die Attach Solder	7.49	mg	Supplier	Silver (Ag)	7440-22-4		0.1873	mg
			А	Lead (Pb)	7439-92-1	7a	6.9282	mg
			Supplier	Tin (Sn)	7440-31-5		0.3745	mg
Lead Frame	3982.39	mg	В	Nickel (Ni)	7440-02-0		9.5577	mg
			Supplier	Iron (Fe)	7439-89-6		5.9736	mg
			Supplier	Copper (Cu)	7440-50-8		3965.2656	mg
			Supplier	Phosphorus (P)	7723-14-0		1.593	mg
Mold Compound-Black	2349.04	mg		Epoxy resin	proprietary data		70.4712	mg
			Supplier	Phenolic Resin	Proprietary Data		35.2356	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		352.356	mg
			Supplier	Carbon Black (C)	1333-86-4		11.7452	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1879.2321	mg
Plating	23.4	mg	Supplier	Tin (Sn)	7440-31-5		23.4	mg
Wire Bond - Al	10.76	mg	Supplier	Aluminum (Al)	7429-90-5		10.76	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).